



See The New World Through i3system, Inc.



Intelligent Image & Information system SEE THE NEW WORLD THROUGH **i3system, Inc.**

Company overview

Company Name : i3system, Inc.
(Intelligent Image & Information System)

CEO : Dr. Han Chung

Establishment : 1998

Number of Employees (2018) : 380 people

- 2001 : R&D center initiated
- 2003 : Cooled IRFPA development initiated
- 2006 : Uncooled IRFPA development initiated
- 2010 : Volume production of cooled IRFPA & IDDCA started
- 2010 : "Defense contractors" designation by Korean Government
- 2015 : Listed on KOSDAQ (Stock market)
- 2015 : ISO9001:2008
- 2017 : Moonji-dong / Factory #2 initiated
- 2018 : ISO9001:2015



Headquarter / Factory #1



Jang-Dong
(R&D Center)



Moonji-dong / Factory #2

Facilities

Process



Assembly



Analysis



Test & Evaluation



**In house manufacture facility
and test equipments**

Contents

01. Cooled MWIR Detector DI1280-10M(1280 × 1024 10μm)	04
02. Cooled MWIR Detector DI1280-15M(1280 × 1024 15μm)	06
03. Cooled MWIR Detector DI640-15M(640 × 512 15μm)	08
04. Cooled MWIR Engine iCE640(640 × 512 15μm)	10
05. Cooled MWIR Detector DI320-30M/15M(320 × 256 30/15μm)	12
06. Cooled MWIR Detector DI320-30Q(QWIP_320 × 256 30μm)	14
07. InGaAs SWIR Detector DS640-15M(640 × 512 15μm)	16
08. InGaAs SWIR Detector DS640-25M(640 × 512 25μm)	18
09. Uncooled LWIR Detector DB1024-12C-A(1024 × 768 12μm)	20
10. Uncooled LWIR Detector DB640-12C-A(640 × 480 12μm)	22
11. Uncooled LWIR Detector DB384-12C-A(384 × 288 12μm)	24
12. Uncooled LWIR Detector DB640-17C-A(640 × 480 17μm)	26
13. Uncooled LWIR Detector DB384-17C-A(384 × 288 17μm)	28
14. Uncooled LWIR Engine TE-EV1(640 × 480 17μm)	30
15. Uncooled LWIR Engine TE-EQ1(384 × 288 17μm)	32
16. Uncooled LWIR Engine TE-EX2/EV2/EQ2(XGA, VGA, QVGA 12μm)	34
17. Uncooled LWIR Engine iE640(640 × 480 17μm)	36
18. Uncooled LWIR Engine iE320M(384 × 288 17μm)	38
19. Mobile LWIR Camera TE-V1(640 × 480 17μm)	40
20. Mobile LWIR Camera TE-V1 Dev. Kit(640 × 480 17μm)	42
21. Mobile LWIR Camera TE-Q1(384 × 288 17μm)	44
22. Mobile LWIR Camera TE-Q1 Dev. Kit(384 × 288 17μm)	46



InSb Cooled IR Detector

InSb 1280 x 1024 10 μ m

DI1280-10M

Array Features

- 1280 x 1024 10 μ m Pitch
- High Operability
- Very High Resolution
- High Sensitivity (Low readout noise, Low dark current)

Applications

- Thermal Imaging System
- Infrared Military System
- Thermal Observation Device (Day and Night)
- Surveillance System



Images from the 2D IR detector

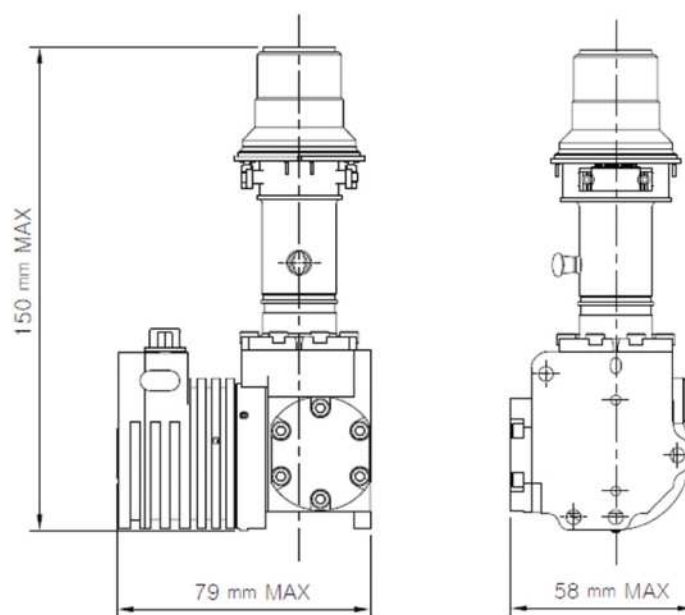


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Specifications

Array format	1280x1024
Pixel pitch	10 μ m
Infrared detector material	InSb
Wavelength band	MWIR (3 μ m~5 μ m)
No. of output channels	4 or 8 channels
Operability	$\geq 99.5\%$ (Typ. $>99.8\%$)
NETD	≤ 25 mK
Max frame rate	100Hz@1280x1024 Full frame
Readout mode	IWR
Cool down time	≤ 7 min.
Environmental condition	MIL-STD-810
Operating temperature	-40~+71 $^{\circ}$ C

DI1280-10M Dimensions



InSb Cooled IR Detector

InSb 1280 x 1024 15 μ m

DI1280-15M

Array Features

- 1280 x 1024 15 μ m Pitch
- High Operability
- Very High Resolution
- High Sensitivity (Low readout noise, Low dark current)

Applications

- Thermal Imaging System
- Infrared Military System
- Thermal Observation Device (Day and Night)
- Surveillance System



Images from the 2D IR detector

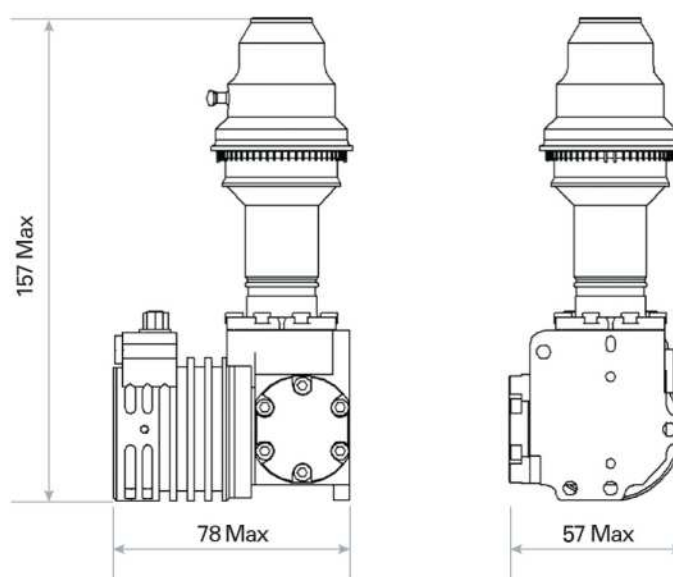


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array format	1280x1024
Pixel pitch	15 μ m
Infrared detector material	InSb
Wavelength band	MWIR (3 μ m~5 μ m)
No. of output channels	4 or 8 channels
Operability	$\geq 99.5\%$ (Typ. $> 99.8\%$)
NETD	≤ 20 mK
Max frame rate	100Hz@ 1280x1024 Full frame
Readout mode	IWR
Cool down time	≤ 7 min.
Environmental condition	MIL-STD-810
Operating temperature	-40~+71 $^{\circ}$ C

DI1280-15M Dimensions



InSb Cooled IR Detector

InSb 640 x 512 15 μ m

DI640-15M

Array Features

- 640x512 15 μ m Pitch
- High Operability

Applications

- Thermal Imaging System
- Infrared Military System
- Thermal Observation Device(Day and Night)
- Surveillance System



Images from the 2D IR detector

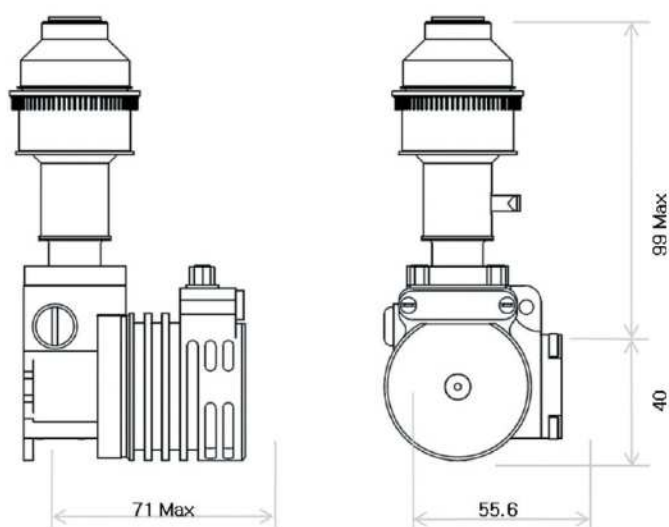


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array format	640 x 512
Pixel pitch	15 μ m
Infrared detector material	InSb
Wavelength band	MWIR (3 μ m~5 μ m)
No. of output channels	1 or 4 channels
Operability	$\geq 99.5\%$ (Typ. > 99.9%)
NETD	≤ 20 mK
Max frame rate	200Hz@640 x 512 Full frame
Readout mode	ITR or IWR
Cool down time	≤ 7 min.
Environmental condition	MIL-STD-810
Operating temperature	-40~+71 $^{\circ}$ C

DI640-15M Dimensions



InSb Cooled IR Engine Gen 2

InSb 640 x 512 15 μ m Detector/Engine

iCE640

Array Features

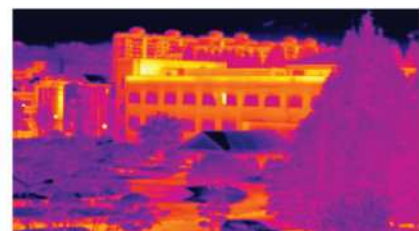
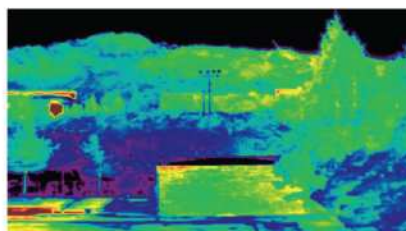
- 640x512 15 μ m Pitch
- High Operability

Applications

- Thermal Imaging System
- Infrared Military System
- Thermal Observation Device (Day and Night)
- Surveillance System



Images from the 2D IR detector

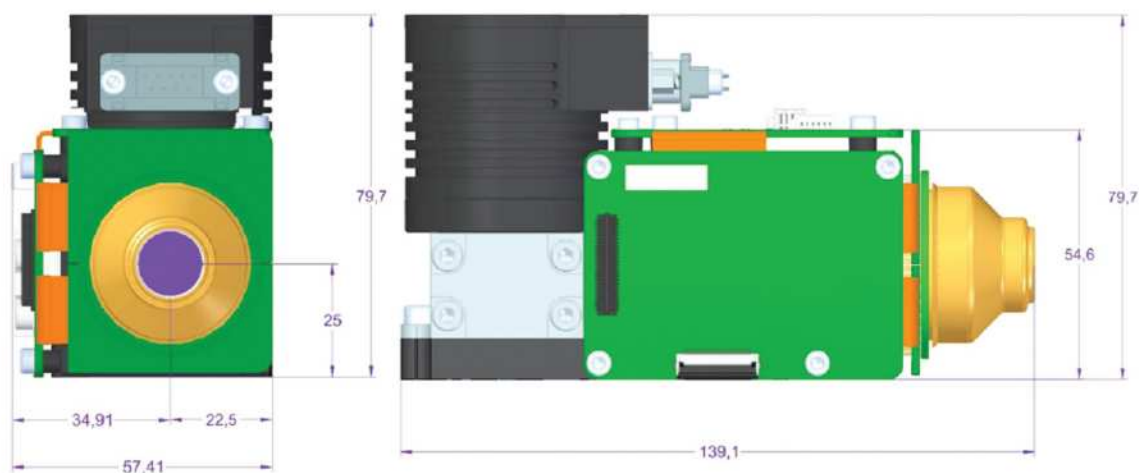


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Detector	
Focal Plane Array	InSb
Array format and pitch	640 x 512, 15 μ m
Thermal sensitivity(NETD)	< 20mK
Spectral range	MWIR(3~5 μ m)
Camera Engine	
Input power supply	DC 24V~28V
Power consumption (Including cooler & electronics)	< 20W@during cool down < 15W@after cool down
Cool down time	$\leq$ 7min.
Max frame rate	200 Hz@ 640 x 512 Full Frame
Video output	Camera Link (Optional : NTSC or PAL)
Control	RS232
Dimensions (WxHxD)	57 x 79 x 139 mm
Weight	< 760g
Operating temperature	-40 ~ +71 $^{\circ}$ C

iCE640 Dimensions



InSb Cooled IR Detector

InSb 320 x 256 30 μ m / 15 μ m

DI320-30M

DI320-15M

Array Features

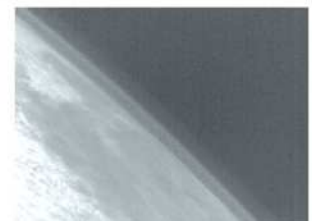
- 320x256/30 μ m pitch
- 320x256/15 μ m pitch
- Excellent Operability

Applications

- Thermal Imaging System
- Infrared Military System
- Thermal Observation Device (Day and Night)
- Surveillance System



Images from the 2D IR detector

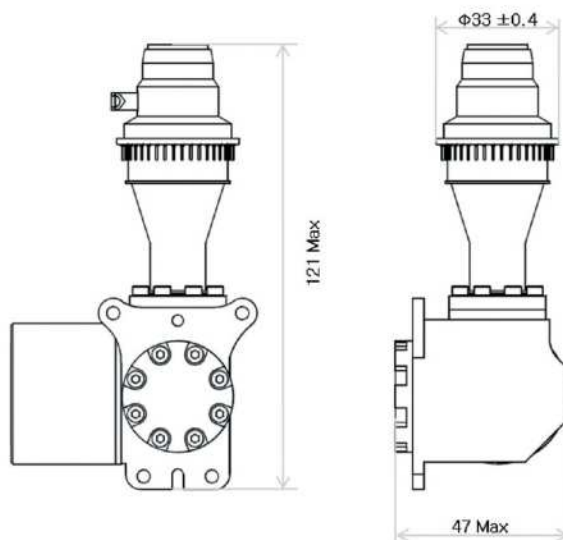


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array format	320 x 256
Pixel pitch	30 μ m or 15 μ m
Infrared detector material	InSb
Wavelength band	MWIR (3 μ m~5 μ m)
No. of output Channels	1 or 4 channels
Operability	$\geq 99.5\%$ (Typ. > 99.9%)
NETD	≤ 20 mK
Readout mode	ITR(30 μ m) / IWR(15 μ m)
Cool down time	≤ 7 min.
Environmental condition	MIL-STD-810
Operating temperature	-40~+71 $^{\circ}$ C

DI320-30M and DI320-15M Dimensions



QWIP Cooled IR Detector

320 x 256 30 μ m (QWIP)

DI320-30Q

Array Features

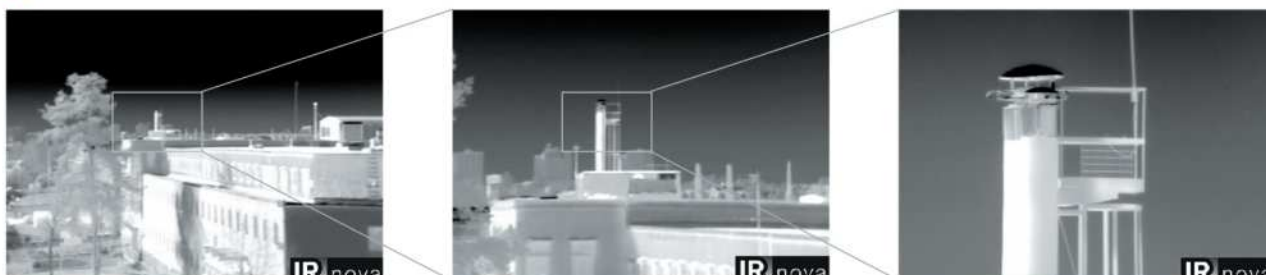
- 320 x 256 30 μ m pitch
- High Operability
- FPA Manufacture : IRnova, Sweden

Applications

- Thermal Imaging System
- Military System
- Surveillance System



Images from the 2D IR detector

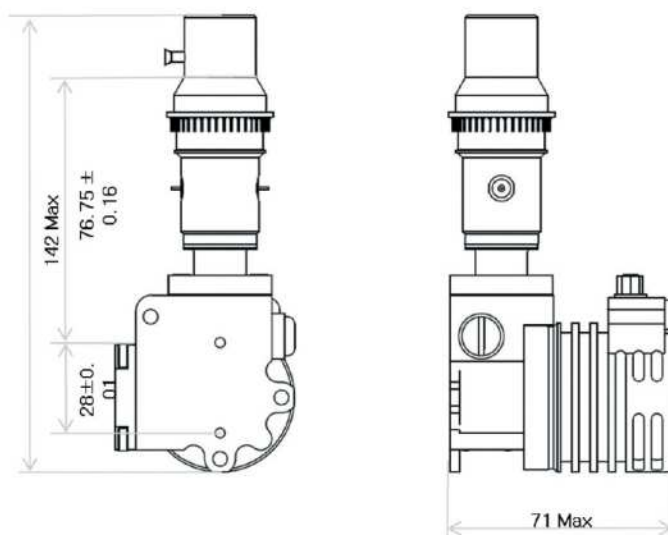


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array format	320 x 256
Pixel pitch	30 μ m
Infrared detector material	QWIP
Wavelength band	LWIR(8.5 μ m~9.0 μ m)
Operability	$\geq 99.5\%$ (Typ. > 99.9%)
NETD	≤ 25 mK
Readout mode	ITR or IWR
Cool down time	< 7m 30s
Environmental condition	MIL-STD-810
Operating temperature	-40~+71 $^{\circ}$ C

DI 320-30Q Dimensions



InGaAs SWIR Detector ($0.9\mu\text{m}\sim 1.7\mu\text{m}$)

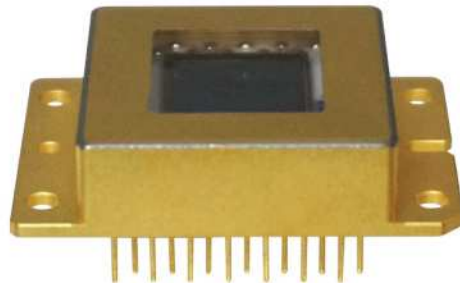
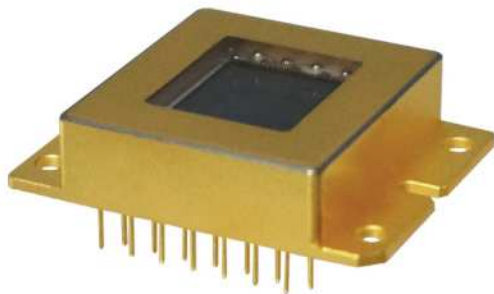
640 x 512 $15\mu\text{m}$ DS640-15M

Array Features

- 640x512 Array Format
- $15\mu\text{m}$ Pixel Pitch
- 28-pin Metal Package
- Thermoelectric Cooler
- Typical Pixel Operability $\geq 99.5\%$

Applications

- Short wave infrared Imaging
- Imaging Spectroscopy
- Surveillance
- Semiconductor Inspection
- Medical Science and Biology
- Astronomy and Scientific



Images from the 2D IR detector

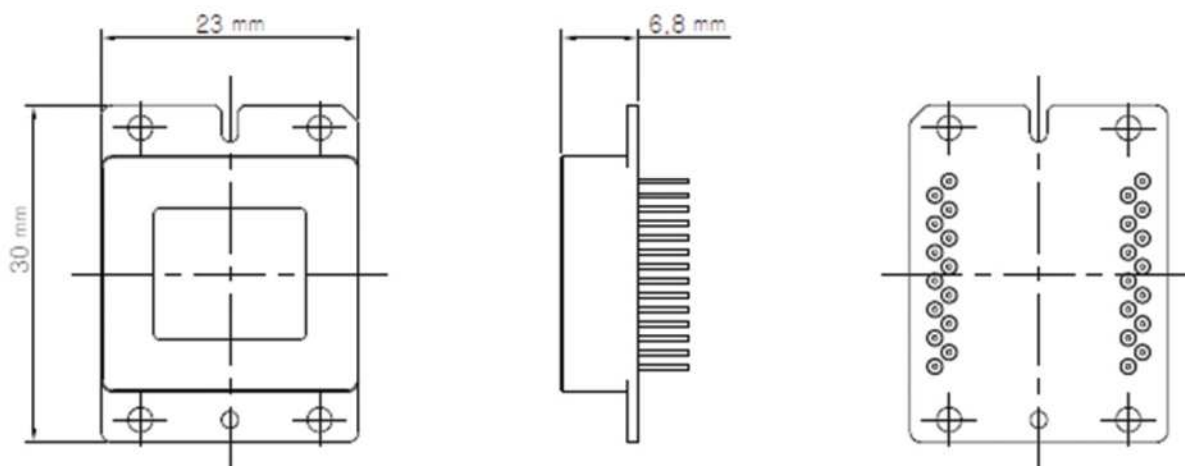


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Specifications

Array Features	
Sensor type	InGaAs
Array format/Pixel Pitch	640 x 512, 15 μ m
Spectral range	SWIR (0.9 μ m~1.7 μ m) Vis-SWIR (0.6 μ m~1.7 μ m) Optional
Detector Features	
Integration time	10 μ s to full frame
Maximum frame rate	30Hz / 60Hz / 100Hz (1ch / 2ch / 4ch)
D* (Detectivity)	$\geq 1.0 \times 10^{13}$ Jones (@1550nm)
Full well	High Gain : 100ke- Low Gain : 1Me-
Output signal swing	2.1V (1.0V to 3.1V)
Input Bias	3.3V
Power consumption	Max. < 5W (@25 $^{\circ}$ C), Max. < 9W (@71 $^{\circ}$ C)
Windowing	Programmable
Temperature sensor output	Yes
Noise with ROIC	$\leq 100e^-$ [HighGain]
Dark current	$\leq 0.2pA@0.1V$ detectorbias
Operability	$\geq 99.5\%$
Operating temperature	-35 $^{\circ}$ C to 71 $^{\circ}$ C
Storage temperature	-40 $^{\circ}$ C to 71 $^{\circ}$ C
Packaging Features	
Dimension (W x H x D)	23 x 30 x 6.8mm
Windows	Sapphire
Number of pins	28
Cooler	Single stage TEC [9W Max]
Packaging characteristics	Hermetically sealed

DS640-15M Dimensions



InGaAs SWIR Detector (0.9 μm ~1.7 μm)

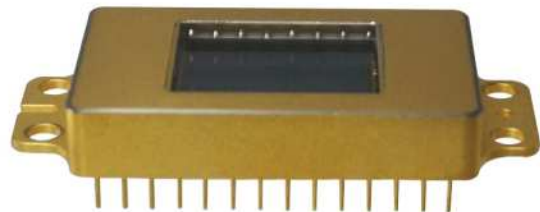
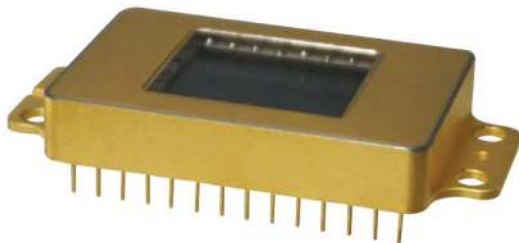
640 x 512 25 μm DS640-25M

Array Features

- 640x512 Array Format
- 25 μm Pixel Pitch
- 28-pin Metal Package
- Thermoelectric Cooler
- Typical Pixel Operability $\geq 99.5\%$

Applications

- Short wave infrared Imaging
- Imaging Spectroscopy
- Surveillance
- Semiconductor Inspection
- Medical Science and Biology
- Astronomy and Scientific



Images from the 2D IR detector

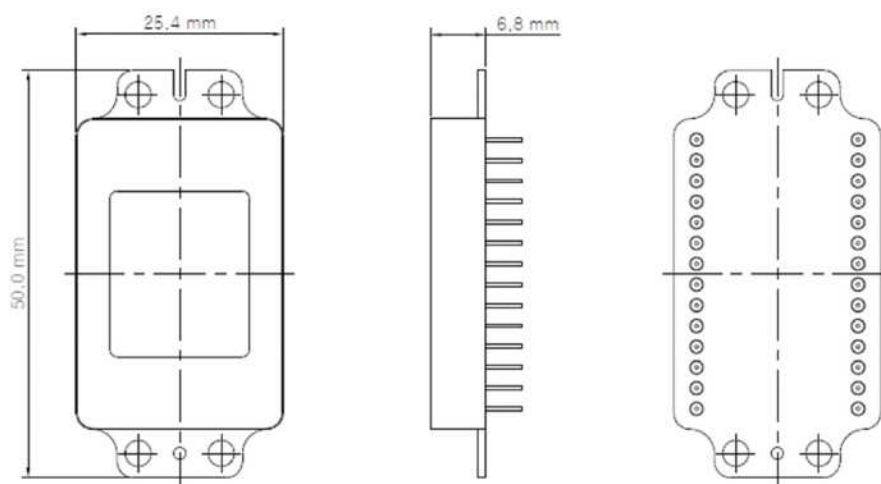


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array Features	
Sensor type	InGaAs
Array format/Pixel Pitch	640 x 512, 25 μ m
Spectral range	SWIR (0.9 μ m~1.7 μ m) Vis-SWIR (0.6 μ m~1.7 μ m) Optional
Detector Features	
Integration time	10 μ s to full frame
Maximum frame rate	30Hz / 60Hz / 100Hz (1ch / 2ch / 4ch)
D* (Detectivity)	$\geq 1.0 \times 10^{13}$ Jones (@1550nm)
Full well	Gain 1: 100ke- Gain 2: 1Me- Gain 3: 4Me- Gain 4: 5Me-
Output signal swing	2.1V (1.0V to 3.1V)
Input Bias	3.3V
Power consumption	Max. < 5W (@25°C), Max. < 9W (@71°C)
Windowing	Programmable
Temperature sensor output	Yes
Noise with ROIC	$\leq 100e^-$ [Gain 1]
Dark current	$\leq 0.2pA@0.1V$ detectorbias
Operability	$\geq 99.5\%$
Operating temperature	-35°C to 71°C
Storage temperature	-40°C to 71°C
Packaging Features	
Dimension (W x H x D)	50 x 25 x 6.8mm
Windows	Sapphire
Number of pins	28
Cooler	Single stage TEC [9W Max]
Packaging characteristics	Hermetically sealed

DS640-25M Dimensions



Uncooled Infrared Detector

LWIR 1024 x 768 12 μ m

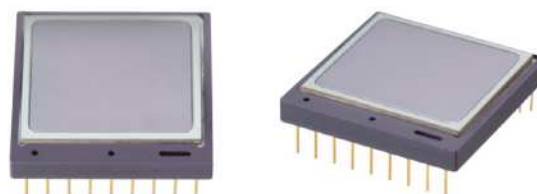
DB1024-12C-A

Overview

DB1024-12C-A is the high performance 1024 x 768, 12 μ m micro-bolometer used in thermal imagers that are designed for commercial and military market. Our higher performance uncooled infrared detector helps infrared camera manufacturers to lead the market in thermography, surveillance & security, car night vision and many other commercial markets, as well as the military market.

Description

- DB1024-12C-A is an uncooled infrared detector with a reliable, small and lightweight, low input power focal plane array.



Ceramic Package

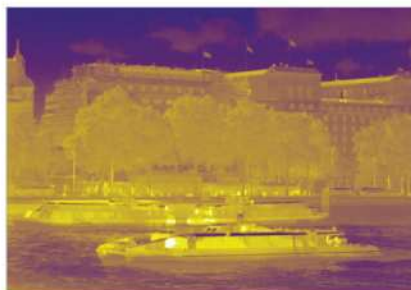
Main Features

- TEClass operation
- Power supply: 5V for analog and digital
- Output dynamic range: 1V to 4V
- Image flip/mirror capability
- 27-lead ceramic vacuum package
- On-chip temperature sensor
- Typical responsivity: 10mV/K
- User defined windowing capability

Applications

- Security-Surveillance
- Night Vision
- Marine Navigation
- Next Generation Rifle
- Health and Medical
- Electrical Machinery Field

Images from the 2D IR detector



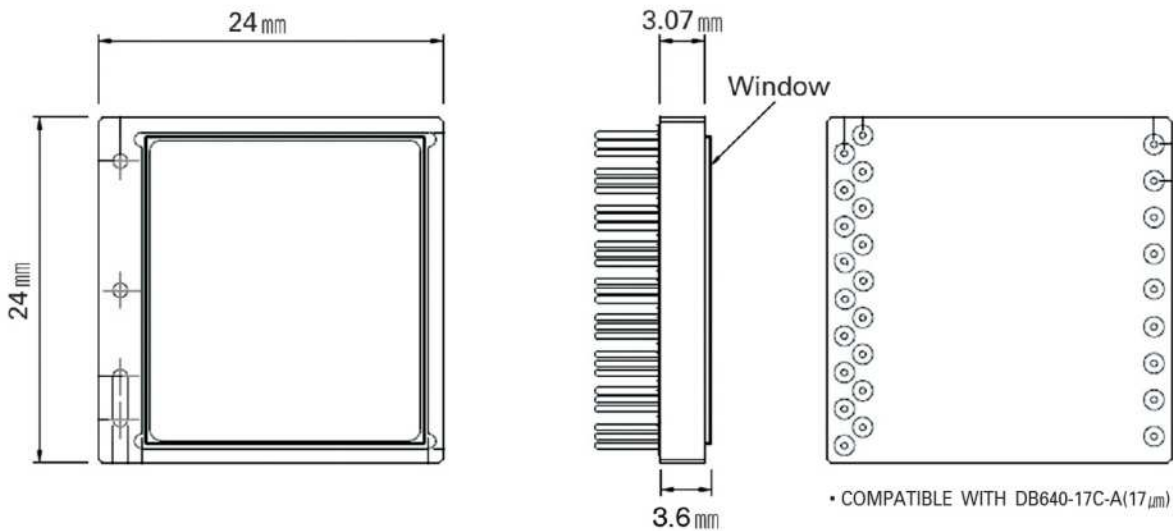
SEE THE NEW WORLD THROUGH

i3system, Inc.

Specifications

Performance	
Detector type	Microbolometer (uncooled)
Array format	1024 x 768
Pixel pitch	12 μ m
NETD	≤ 45 mK or ≤ 50 mK @ F/1, 300K, 30Hz
Operability	$\geq 99\%$
Frame rate	Max 30Hz
Video output	2ch
Thermal time constant	≤ 15 ms
Operating temperature	-40 $^{\circ}$ C ~ 65 $^{\circ}$ C
Features	
Wavelength band	LWIR
Spectral range	8 ~ 14 μ m
Dimensions	24(W) x 24(H) x 3.6(D)mm ³ (Without pin)
Weight	≤ 7 g
Windowing	Windowing capability

DB1024-12C-A Dimensions



Uncooled Infrared Detector

LWIR 640 x 480 12 μ m

DB640-12C-A

Overview

DB640-12C-A is the high performance 640 x 480, 12 μ m micro-bolometer used in thermal imagers that are designed for commercial and military market. Our higher performance uncooled infrared detector helps infrared camera manufacturers to lead the market in thermography, surveillance & security, car night vision and many other commercial markets, as well as the military market.

Description

- DB640-12C-A is an uncooled infrared detector with a reliable, small and lightweight, low input power focal plane array.



Ceramic Package



WLP Package

Main Features

- TECless operation
- Power supply: 5V for analog and digital
- Output dynamic range: 1V to 4V
- Image flip/mirror capability
- 27-lead ceramic vacuum package
- On-chip temperature sensor
- Typical responsivity: 10mV/K
- User defined windowing capability

Applications

- Security-Surveillance
- Night Vision
- Marine Navigation
- Next Generation Rifle
- Health and Medical
- Electrical Machinery Field

Images from the 2D IR detector

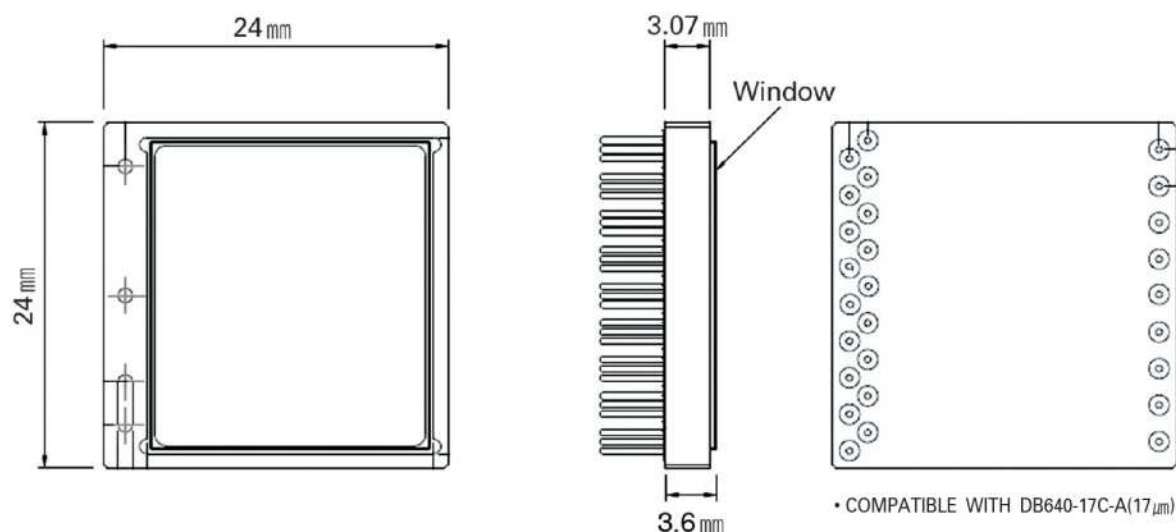


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Performance	
Detector type	Microbolometer (uncooled)
Array format	640 x 480
Pixel pitch	12 μm
NETD	$\leq 40\text{mK}$ or $\leq 50\text{mK}$ @ F/1, 300K, 30Hz
Operability	$\geq 99\%$
Frame rate	Max 60Hz @ 2ch
	Max 30Hz @ 1ch
Video output	1ch or 2ch (Selectable)
Thermal time constant	$\leq 15\text{ms}$
Operating temperature	$-40^{\circ}\text{C} \sim 65^{\circ}\text{C}$
Features	
Wavelength band	LWIR
Spectral range	8 ~ 14 μm
Dimensions	24(W) x 24(H) x 3.6(D) mm^3 (Without pin)
Weight	$\leq 7\text{g}$
Windowing	Windowing capability

DB640-12C-A Dimensions



Uncooled Infrared Detector

LWIR 384 x 288 12 μ m

DB384-12C-A

Overview

DB384-12C-A is the high performance 384 x 288, 12 μ m micro-bolometer used in thermal imagers that are designed for commercial and military market. Our higher performance uncooled infrared detector helps infrared camera manufacturers to lead the market in thermography, surveillance & security, car night vision and many other commercial markets, as well as the military market.

Description

- DB384-12C-A is an uncooled infrared detector with a reliable, small and lightweight, low input power focal plane array.



Ceramic Package



WLP Package

Main Features

- TECless operation
- Power supply: 5V for analog and digital
- Output dynamic range: 1V to 4V
- Image flip/mirror capability
- 44-leadless ceramic vacuum package
- On-chip temperature sensor
- Typical responsivity: 10 mV/K
- User defined windowing capability

Applications

- Security-Surveillance
- Night Vision
- Marine Navigation
- Next Generation Rifle
- Health and Medical

Images from the 2D IR detector

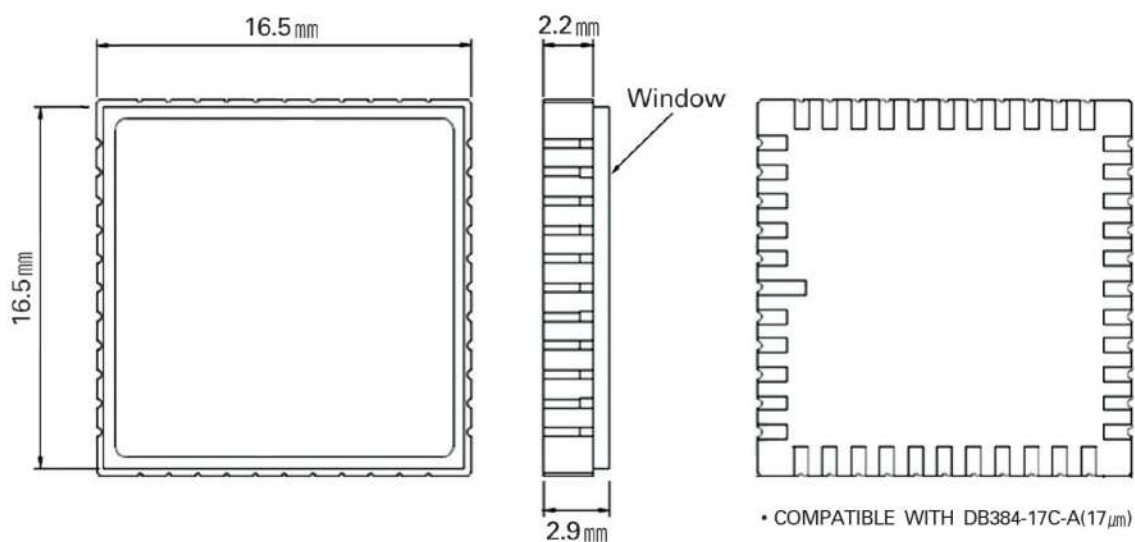


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Specifications

Performance	
Detector type	Microbolometer (uncooled)
Array format	384 x 288
Pixel pitch	12 μm
NETD	$\leq 50\text{mK}@ F/1, 300\text{K}, 30\text{Hz}$
Operability	$\geq 99\%$
Frame rate	Max 60Hz
Video output	1 ch
Thermal time constant	$\leq 15\text{ms}$
Operating temperature	$-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$
Features	
Wavelength band	LWIR
Spectral range	$8 \sim 14\mu\text{m}$
Dimensions	16.5(W) x 16.5(H) x 2.9(D) mm ³
Weight	$\leq 3\text{g}$
Windowing	Windowing capability

DB384-12C-A Dimensions



Uncooled Infrared Detector

LWIR 640 x 480 17 μ m

DB640-17C-A

Overview

DB640-17C-A is the high performance 640 x 480, 17 μ m micro-bolometer designed for industrial-commercial thermal imagers. Our higher performance uncooled infrared detector helps infrared camera manufacturers to lead the market in thermography, surveillance & security, car night vision and many other commercial markets, as well as the military market.

Description

- DB640-17C-A is an uncooled infrared detector with a reliable, small and lightweight, low input power focal plane array.



Ceramic Package

Key Features

- TECless operation
- Power supply : 5V for analog and digital
- Output dynamic range : 1V to 4V
- Image flip/mirror capability
- 27-lead ceramic vacuum package
- On-chip/Off-chip dual temperature sensor
- Typical responsivity : 10mV/K
- User defined windowing capability

Applications

- Security / Surveillance
- Night Vision
- Marine Navigation
- Next Generation Rifle
- Health and Medical
- Electrical machinery field

Images from the 2D IR detector

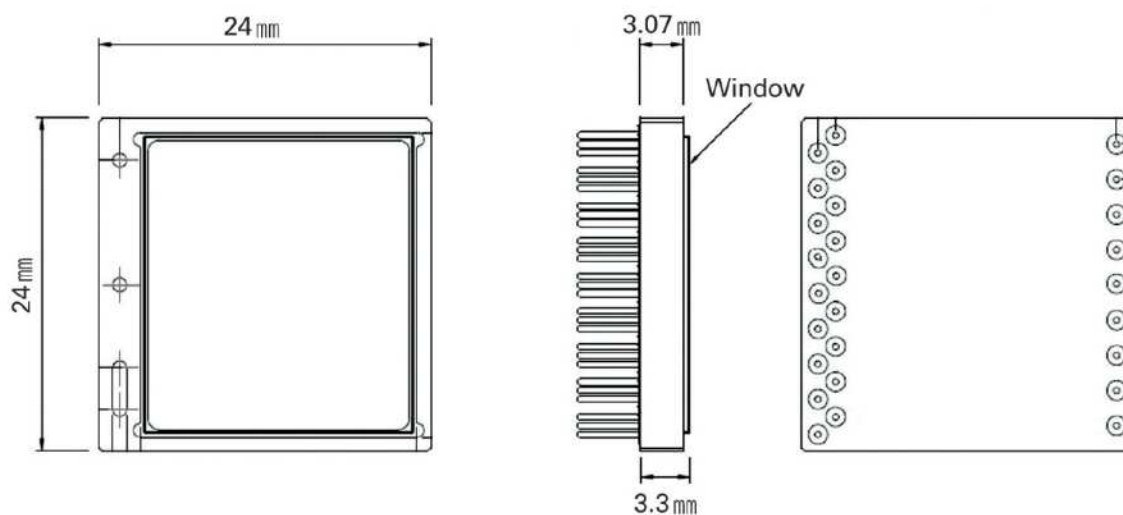


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Performance	
Detector type	Microbolometer (uncooled)
Array format	640 x 480
Pixel pitch	17 μm
Thermal Sensitivity (NETD)	$\leq 50 \text{ mK@F/1, 300K, 30Hz}$
	$\leq 35 \text{ mK@F/1, 300K, 30Hz (Optional)}$
Operability	$\geq 99 \%$
Frame rate	Max 60 Hz @ 2ch
	Max 30 Hz @ 1ch
Video output	1ch or 2ch (Selectable)
Thermal time constant	$\leq 15 \text{ ms}$
Operating temperature	$-40^{\circ}\text{C} \sim 65^{\circ}\text{C}$
Features	
Wavelength band	LWIR
Spectral range	8 ~ 14 μm
Dimensions	24 (W) x 24 (H) x 3.3 (D) mm^3 (Without pin)
Weight	$\leq 7 \text{ g}$
Windowing	Windowing capability

DB640-17C-A Dimensions



Uncooled Infrared Detector

LWIR 384 x 288 17 μm

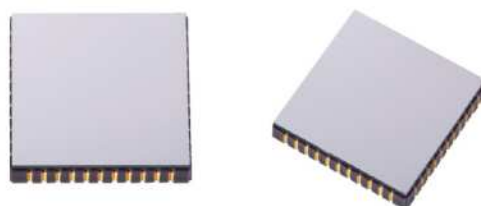
DB384-17C-A

Overview

DB384-17C-A is the high performance 384 x 288, 17 μm micro-bolometer designed for industrial-commercial thermal imagers. Our higher performance uncooled infrared detector helps infrared camera manufacturers to lead the market in thermography, surveillance & security, car night vision and many other commercial markets, as well as the military market.

Description

- DB384-17C-A is an uncooled infrared detector with a reliable, small and lightweight, low input power focal plane array.



Ceramic Package

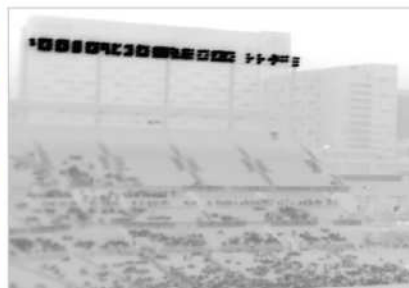
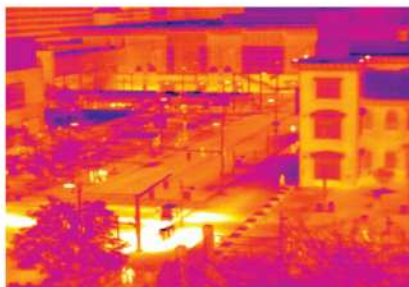
Main Features

- TECless operation
- Power supply: 5V for analog and digital
- Output dynamic range: 1V to 4V
- Image flip/mirror capability
- 44-leadless ceramic vacuum package
- On-chip/Off-chip dual temperature sensor
- Typical responsivity: 10 mV/K
- User defined windowing capability

Applications

- Security-Surveillance
- Night Vision
- Marine Navigation
- Next Generation Rifle
- Health and Medical

Images from the 2D IR detector

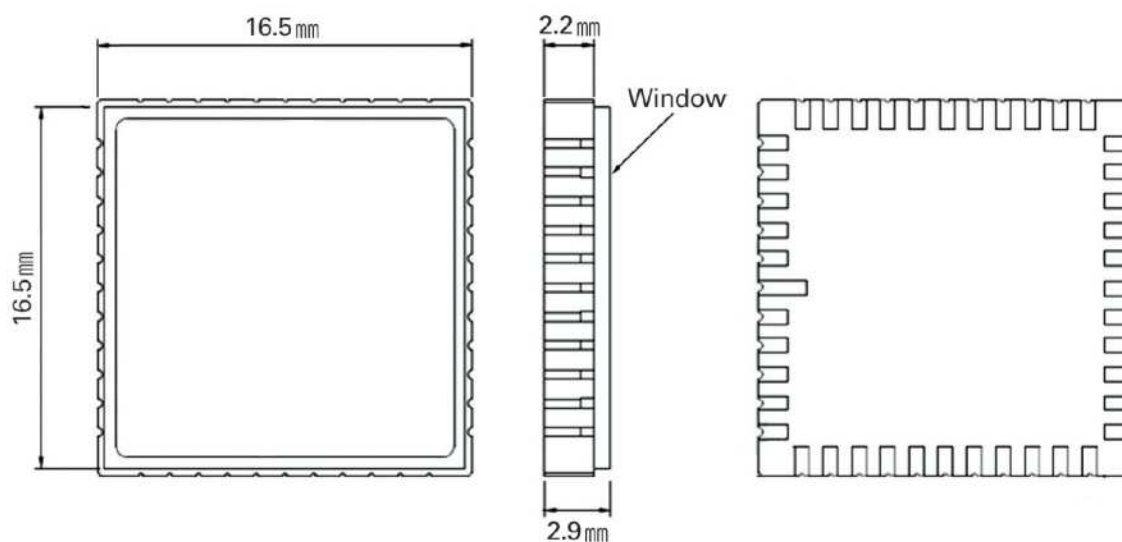


SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Performance	
Detector type	Microbolometer (uncooled)
Array format	384 x 288
Pixel pitch	17 μm
NETD	$\leq 50\text{mK @ F/1, 300K, 30Hz}$
Operability	$\geq 99\%$
Frame rate	Max 60Hz
Video output	1ch
Thermal time constant	$\leq 15\text{ms}$
Operating temperature	$-40\text{ }^{\circ}\text{C} \sim 65\text{ }^{\circ}\text{C}$
Features	
Wavelength band	LWIR
Spectral range	8 ~ 14 μm
Dimensions	16.5(W) x 16.5(H) x 2.9(D) mm^3
Weight	$\leq 4\text{g}$
Windowing	Windowing capability

DB384-17C-A Dimensions



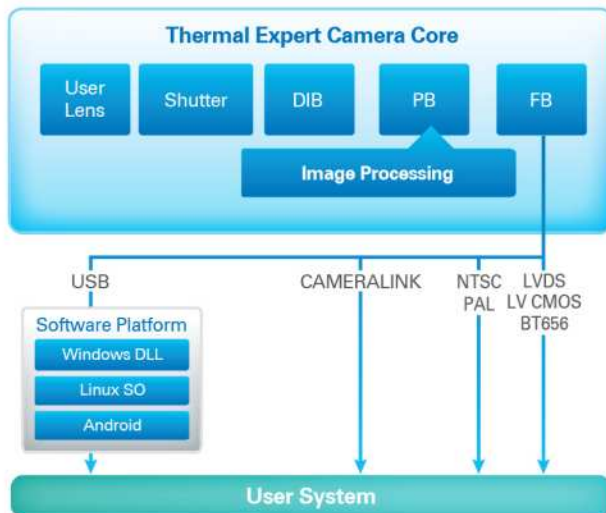
THERMAL EXPERT™

Uncooled Infrared Engine

TE-EV1

Description

TE-EV1 is an infrared camera system which integrates a 640 x 480 17μm pitch, long-wave infrared (LWIR) micro bolometer, shutter, signal processing electronics (DIB, PB, FB) and selectable lenses.



Component

- DIB (Detector Interface Board) : A/D converting of Detector data.
- PB (Process Board) : Detector control and image processing.
- FB (Feature Board) : Output board.
 - USB output mode
 - Camera Link output mode
 - LVDS or LV CMOS or BT656 output mode
 - NTSC or PAL output mode

Applications

- Security / Surveillance
- Night Vision
- Marine Navigation
- Medical Application
- Electrical Maintenance



Images from Thermal Expert Engine



SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

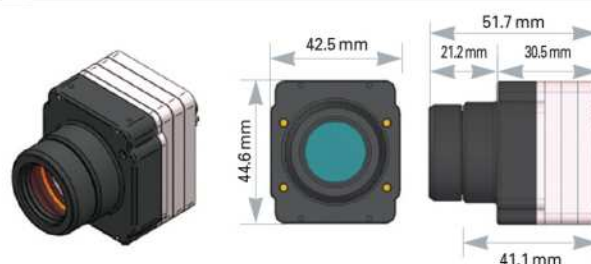
Detector	
Detector type	Micro-Bolometer (uncooled)
Array format	640 x 480
Pixel pitch	17 μ m
Thermal sensitivity (NETD)	≤ 50 mK@F/1, 300K ≤ 35 mK@F/1, 300K(Optional)
Spectral range	8 to 14 μ m
Camera Engine	
Power supply	DC 5V
Power consumption	<2.0 W @ (30Hz)
Video output format	Digital : Camera Link, USB, LVDS, LV CMOS, BT656, IP(OnVif) Analog : NTSC, PAL
Control	USB2.0, RS-232, I2C, UART
Frame rate	30 Hz or 60 Hz
Time to First Image	< 10 sec
Dimensions (WxHxD) (with lens mount)	42.5 mm x 44.6 mm x 41.1 mm
Weight	< 110 g (without lens)
Operating temperature	-10 $^{\circ}$ C ~ 65 $^{\circ}$ C (-40 $^{\circ}$ C ~ 65 $^{\circ}$ C optional)
Storage temperature	-40 $^{\circ}$ C ~ 85 $^{\circ}$ C
Scene range temperature	-10 $^{\circ}$ C ~ 150 $^{\circ}$ C (at Digital output)

Lens Information

Focal Length	F-number	FOV (H x V - Diagonal)
8.5 mm	F/1.2	73.2 x 54.5 - 93.3
19 mm	F/1.0	32.3 x 24.4 - 40.1
25 mm	F/1.2	24.2 x 18.4 - 29.8
35 mm	F/1.1	17.0 x 13.0 - 20.9

TE-EV1 Dimensions

(Unit mm)



Range Performance



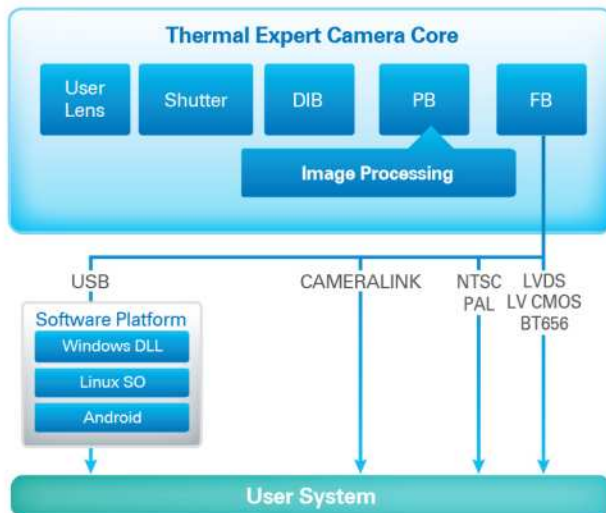
THERMAL EXPERT™

Uncooled Infrared Engine

TE-EQ1

Description

TE-EQ1 is an infrared camera system which integrates a 384x288 17μm pitch, long-wave infrared (LWIR) micro bolometer, shutter, signal processing electronics (DIB, PB, FB) and selectable lenses.



Components

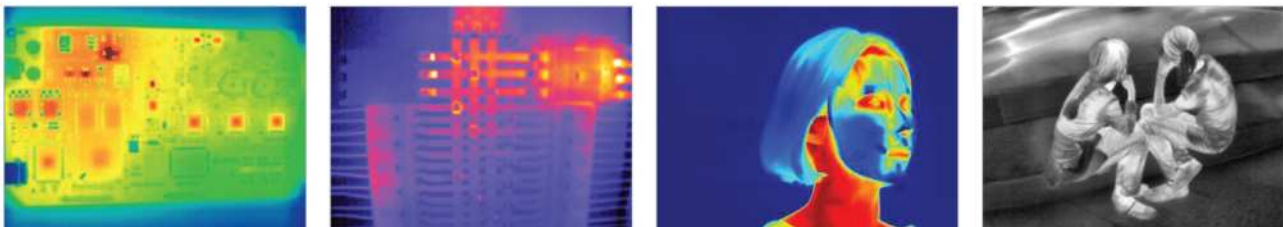
- DIB (Detector Interface Board) : A/D converting of Detector data.
- PB (Process Board) : Detector control and image processing.
- FB (Feature Board) : Output board.
 - USB output mode
 - Camera Link output mode
 - LVDS or LV CMOS or BT656 output mode
 - NTSC or PAL output mode

Applications

- Security / Surveillance
- Night Vision
- Marine Navigation
- Medical Application
- Electrical Maintenance



Images from Thermal Expert Engine



SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

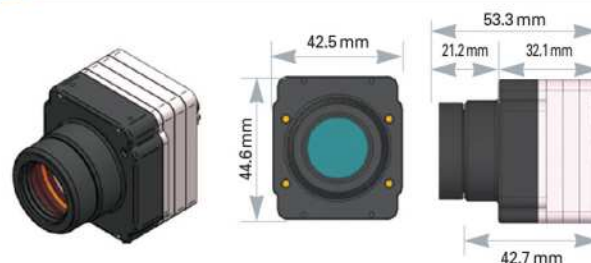
Detector	
Detector type	Micro-Bolometer (uncooled)
Array format	384 x 288
Pixel pitch	17 μ m
Thermal sensitivity(NETD)	≤ 50 mK@F/1, 300K
Spectral range	8 to 14 μ m
Camera Engine	
Power supply	DC 5V
Power consumption	< 1.8W @ (30Hz)
Video output format	Digital : Camera Link, USB, LVDS, LV CMOS, BT656, IP(OnVif) Analog : NTSC, PAL
Control	USB2.0, RS-232, I2C, UART
Frame rate	30 Hz or 60 Hz
Time to First Image	< 10 sec
Dimensions (W x H x D) (with lens mount)	42.5 mm x 44.6 mm x 42.7 mm
Weight	< 110g (without lens)
Operating temperature	-10 $^{\circ}$ C ~ 65 $^{\circ}$ C (-40 $^{\circ}$ C ~ 65 $^{\circ}$ C optional)
Storage temperature	-40 $^{\circ}$ C ~ 85 $^{\circ}$ C
Scene range temperature	-10 $^{\circ}$ C ~ 150 $^{\circ}$ C (at Digital output)

Lens Information

Focal Length	F-number	FOV(H x V - Diagonal)
6.8mm	F/1.4	56.3 x 41.8 - 71.4
8.5mm	F/1.2	43.5 x 32.8 - 54.7
13mm	F/1.0	28.7 x 21.7 - 35.3
19mm	F/1.0	19.6 x 14.7 - 24.4
25mm	F/1.2	14.8 x 11.1 - 18.4
35mm	F/1.1	10.5 x 7.9 - 13.0

TE-EQ1 Dimensions

(Unit mm)



Range Performance



THERMAL EXPERT™

Uncooled Infrared Engine

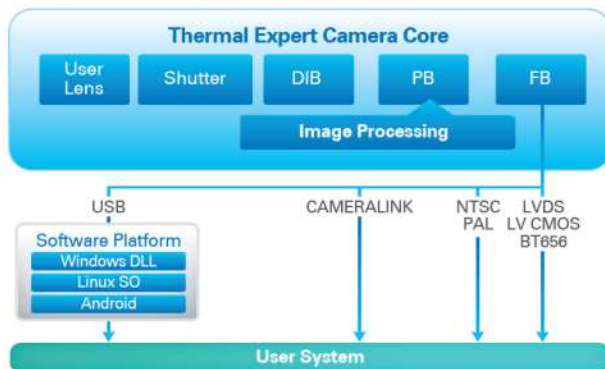
TE-EX2/EV2/EQ2

Description

TE-EX2/EV2/EQ2 is an infrared camera system which integrates a long-wave infrared (LWIR) micro bolometer, shutter, signal processing electronics (DIB, PB, FB) and selectable lenses.

Components

- DIB (Detector Interface Board) : A/D converting of Detector data.
- PB (Process Board) : Detector control and image processing.
- FB (Feature Board) : Output board.
 - USB output mode
 - Camera Link output mode
 - LVDS or LV CMOS or BT656 output mode
 - NTSC or PAL output mode



TE-EQ2 (Module)



TE-EX/EV2 (Module)



* Including lens

Images from Thermal Expert Engine



SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

	TE-EQ2	TE-EV2	TE-EX2
Detector Type	Micro-Bolometer(Uncooled)		
Array format and Pitch	384x288, 12 μ m	640x480, 12 μ m	1024x768 12 μ m
Thermal Sensitivity(NETD)	50mK / F#1.0, Room Temperature		
Spectral Range	8 to 14 μ m		
Power Supply	DC 5V (<0.46A)	DC 5V (<0.5A)	DC 5V (<0.5A)
Power Consumption	<1.6W@30Hz(Steady State)	<2.0W@30Hz(Steady State)	<2.5W@30Hz(Steady State)
Video Output Format	Digital : USB, CameraLink, LVCMOS 3.3V, LVDS,BT656 Analog : NTSC, PAL		
Frame Rate	30Hz		
Time to First Image	<7 Sec Max.(Typ. <6 sec)		
Control Command Protocols	RS-232(Optional RS-485)		
Dimensions(WxHxD)	30x30x27 mm	30x36x27 mm	30x36x27 mm
Weight	<50g(Without Lens)		
Operating Temperature	-10 $^{\circ}$ C ~ 65 $^{\circ}$ C (Optional -40 $^{\circ}$ C ~ 65 $^{\circ}$ C)		
Storage Temperature	-40 $^{\circ}$ C ~ 85 $^{\circ}$ C		
Scene Range Temperature	-10 $^{\circ}$ C ~ 150 $^{\circ}$ C (Optional 0 $^{\circ}$ C ~ 500 $^{\circ}$ C)		

Lens Information

	F/L	FOV(H x V)	Mount
TE-EX2 1024x768 12 μ m	13mm@f/1.0	54 x 40.6	M34 x 0.75
	19mm@f/1.0	38.4 x 28.4	M34 x 0.75
	25mm@f/1.0	27.7 x 20.9	M34 x 0.75
	35mm@f/1.0	20 x 15.1	M45 x 1
	50mm@f/1.2	13.9 x 10.5	M45 x 1

	F/L	FOV(H x V)	Mount
TE-EV2 640x480 12 μ m	4.9mm@f/1.0	95 x 69.6	M24 x 0.5
	8.7mm@f/1.0	50.8 x 38	M24 x 0.5
	13.5mm@f/1.0	32 x 24	M24 x 0.5
	18mm@f/1.0	24 x 18.1	M24 x 0.5
	24mm@f/1.0	18 x 13.6	M24 x 0.5

	F/L	FOV(H x V)	Mount
TE-EQ2 384x288 12 μ m	2.5mm@f/1.0	110.4 x 81.2	M18 x 0.5
	4.4mm@f/1.0	60.4 x 44.9	M18 x 0.5
	6.3mm@f/1.0	42.2 x 31.6	M18 x 0.5
	9.1mm@f/1.0	28.4 x 19.3	M18 x 0.5
	13.5mm@f/1.0	19.3 x 14.5	M24 x 0.5
	18mm@f/1.0	14.5 x 10.9	M24 x 0.5

Uncooled Infrared Camera Engine

640 x 480 17 μm

iE640

Introduction

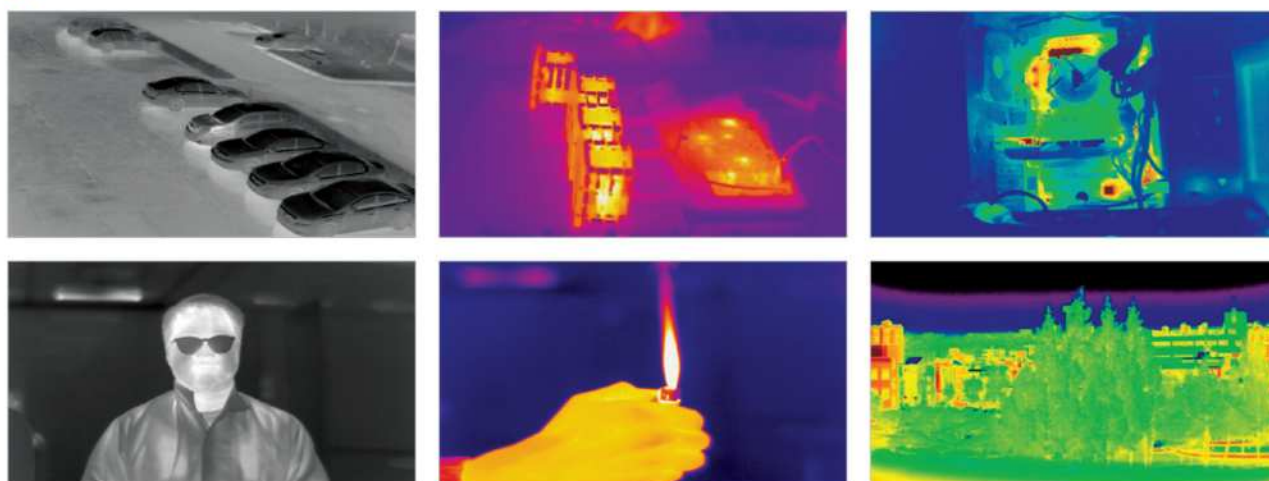
The Infrared Camera Core of iE640 consists of an Uncooled Infrared detector for LWIR(Long Wavelength Infrared,) 8~14 μm range and Circuit Board for Imaging Processing, which can be used as the Detector and core IR camera.

Applications

- Security-Surveillance
- Night Vision
- Marine Navigation
- Medical Application
- Electrical Maintenance
- Non Destructive Test
- Temperature Measurement



Images from the iE640

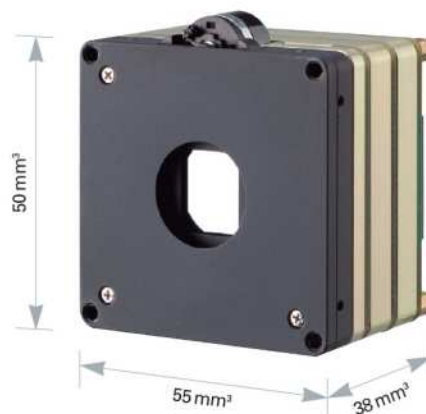


SEE THE NEW WORLD THROUGH i3system, Inc.

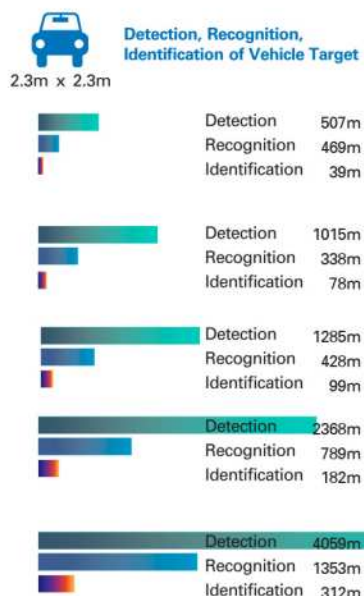
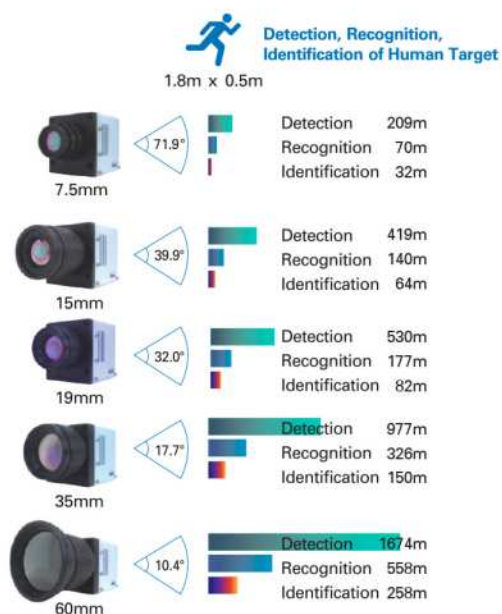
Specifications

Detector	
Detector type	Microbolometer
Array format	640 x 480
Pixel Pitch	17 μ m
Thermal sensitivity(NETD)	<50mK at F/1.0
Spectral range	8~14 μ m
Camera Engine	
Input power supply	DC 9~12V
Power consumption	< 1.5W (at Room temperature)
Output format	640 x 480, 30Hz
Video output	16bit TTL 3.3V Level
Time to Image	<5sec
Scene temperature range	-20 ~ 120 $^{\circ}$ C -20 ~ 650 $^{\circ}$ C (Optional)
Control	I 2 C
Dimensions(W x H x D)	55 x 50 x 38mm ³
Weight	126g
Operating temperature	-10 $^{\circ}$ C ~ 65 $^{\circ}$ C (-40 $^{\circ}$ C ~ 65 $^{\circ}$ C optional)

iE640 Dimensions



Range Performance



Uncooled Infrared Camera Engine

384 x 288 17 μm

iE320M

Introduction

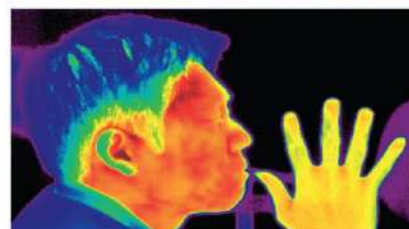
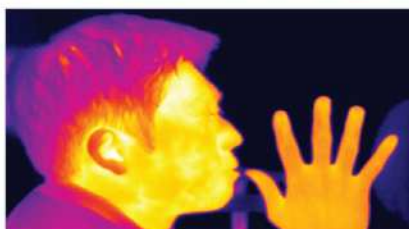
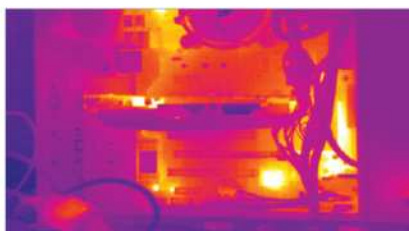
The Infrared Camera Core of iE320M consist of an Uncooled Infrared detector for LWIR(Long Wavelength Infrared,) 8~14 μm range and Circuit Board for Imaging Processing, which can be used as the Detector and core IR camera.

Applications

- Security-Surveillance
- Night Vision
- Marine Navigation
- Medical Application
- Electrical Maintenance
- Non Destructive Test
- Temperature Measurement



Images from the iE320M

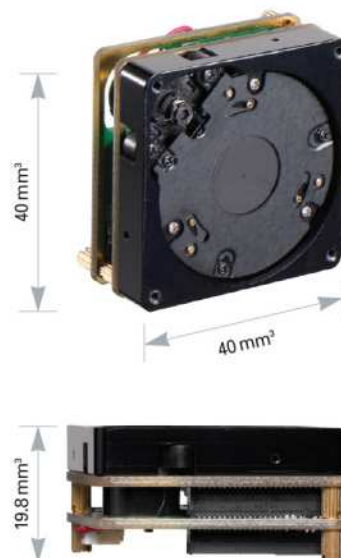


SEE THE NEW WORLD THROUGH i3system, Inc.

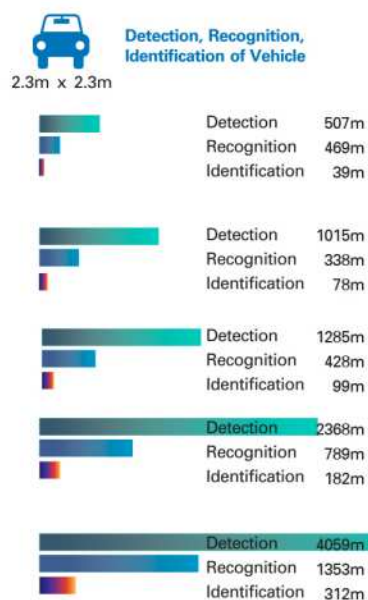
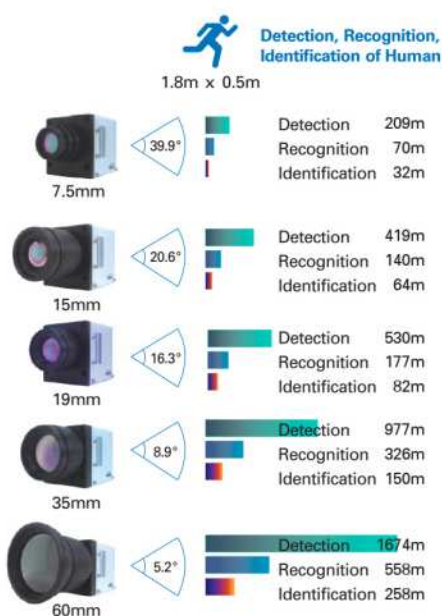
Specifications

Detector	
Detector type	Microbolometer
Array format	384 x 288
Pixel Pitch	17 μ m
Thermal sensitivity(NETD)	<50mK at F/1.0
Spectral range	8~14 μ m
Camera Engine	
Input power supply	DC 5V($\pm$ 10%)
Power consumption	< 1.2 W(at Room temperature)
Output format	384 x 288, 30Hz
Video output	16bit TTL 3.3V Level NTSC/PAL Video(Optional)
Time to Image	< 5sec
Scene temperature range	- 20 ~ 120 $^{\circ}$ C - 20 ~ 650 $^{\circ}$ C (Optional)
Control	RS232
Dimensions(WxHxD)	40 x 40 x 19.8mm ³
Weight	< 36g
Operating temperature	-10 $^{\circ}$ C ~ 65 $^{\circ}$ C (-40 $^{\circ}$ C ~ 65 $^{\circ}$ C optional)

iE320M Dimensions



Range Performance



THERMAL EXPERT™

Mobile Infrared Camera

TE-V1



8.5mm lens
Optional



19mm lens
Default



25mm lens
Optional



35mm lens
Optional

Description

- High performance
- High resolution : 640 x 480 (17 μ m pitch)
- High sensitivity : < 50 mk



Features

- Temperature measurement for whole pixel
- Superior image with native 307,200 pixels(640x480) resolution
- Interchangeable Lens
- Shutterless operation
- Easy graphical user interface
- Optional Lens(8.5mm/25mm/35mm)

THERMAL EXPERT™ for Android

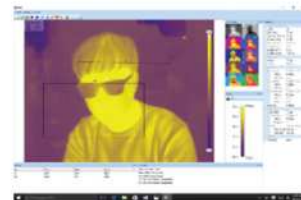
- Color palettes(12 color maps)
- Storage images(IR, visible with snapshot and video)
- Digital zooming(640 x 480, 480 x 360, 384 x 288, 240 x 180)
- Image view with visible(50:50, Twin, Overlay, Floating)
- Temperature Measurement
(Alarm, Min/Max, Point/Line/Rectangle/Circle profile)
- Report(Generate pdf report)
- Level and Span function



Level and Span

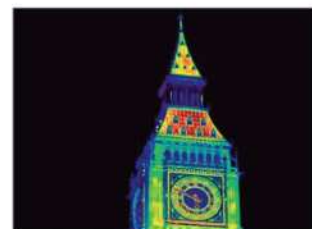
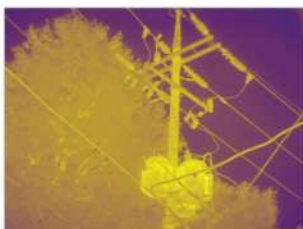
THERMAL EXPERT™ for Windows

- Realtime Analysis Tool
- Check the temperature anywhere in picture using mark of Dot, Line, Square
- Alarm with sound by user's setting temperature degree
- Save and Load infrared Image with mark
- Saving the movie with mark is being implemented
- AIE Program(Adaptive Image Enhancement)



Window PC program

Images from the THERMAL EXPERT™



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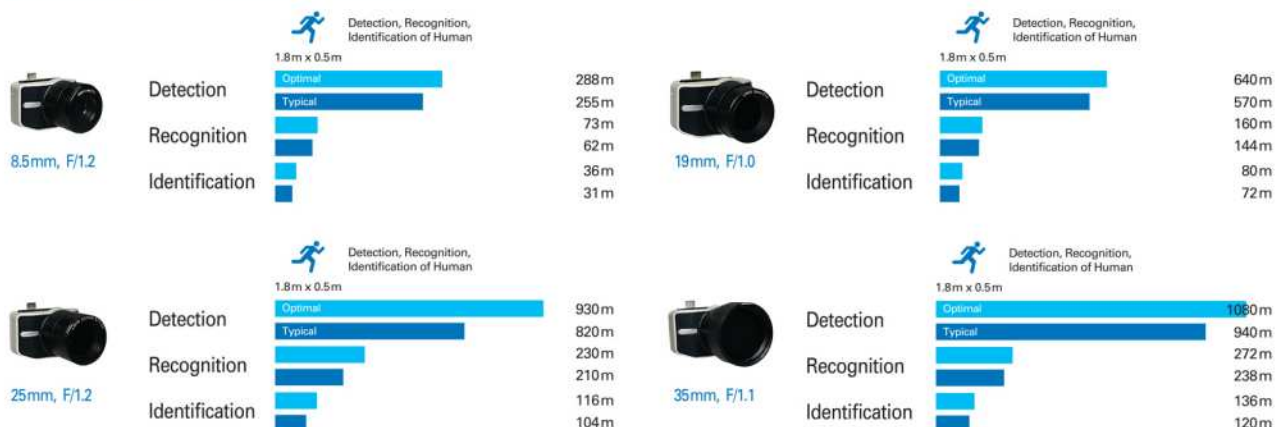
Specifications

Array Format	640 x 480
Pixel pitch	17 μ m
Wavelength band	8~14 μ m (Longwave infrared)
Sensitivity	$\leq 50\text{mK}@F/1, 300\text{K}$
Frame rate	< 9 Hz or 30 Hz (Export Licence)
Scene range temperature	-10 $^{\circ}\text{C}$ ~ 120 $^{\circ}\text{C}$
Operating temperature	-10 $^{\circ}\text{C}$ ~ 50 $^{\circ}\text{C}$
Power Consumption	$\leq 500\text{mW}$
Weight	< 60g, without lens
Dimensions	50 mm x 32 mm x 30 mm, without Lens
Interface	Micro USB
Platform	Android, Windows
Type of lens	8.5mm, F/1.2(Optional)
	19mm, F/1.0(Default)
	25mm, F/1.2(Optional)
	35mm, F/1.1(Optional)
FOV	8.5 mm : 73.2 $^{\circ}$ (H) x 54.5 $^{\circ}$ (V) - 93.3 $^{\circ}$ (diagonal)
	19 mm : 32.3 $^{\circ}$ (H) x 24.4 $^{\circ}$ (V) - 40.1 $^{\circ}$ (diagonal)
	25 mm : 17.3 $^{\circ}$ (H) x 13.1 $^{\circ}$ (V) - 21.5 $^{\circ}$ (diagonal)
	35 mm : 12.3 $^{\circ}$ (H) x 9.3 $^{\circ}$ (V) - 15.2 $^{\circ}$ (diagonal)
Focus range	8.5 mm : 0.4 m to infinity
	19 mm : 2.4 m to infinity
	25 mm : 1.0 m to infinity
	35 mm : 5.0 m to infinity

TE-V1 Dimensions



Range Performance



THERMAL EXPERT™

Mobile Infrared Camera_Dev. Kit

TE-V1 Dev. Kit



8.5mm lens
Optional



19mm lens
Default



25mm lens
Optional



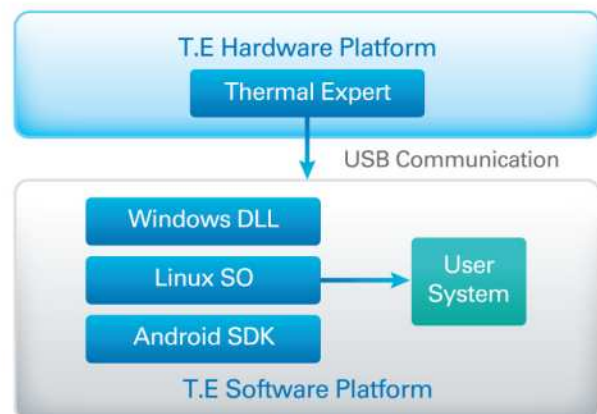
35mm lens
Optional

Description

- High performance
- High resolution : 640 x 480 (17 μ m pitch)
- High sensitivity : < 50 mk

Features

- Temperature measurement for whole pixel
- Superior image with native 307,200pixels(640x480) resolution
- Interchangeable Lens
- Shutterless operation
- Easy graphical user interface
- Optional Lens(8.5mm / 25mm / 35mm)



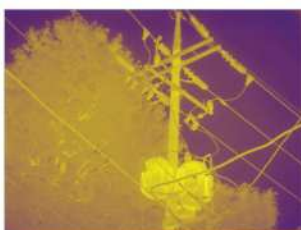
T.E. Software Platform

- The platform of T.E. software includes Non-Uniformity Correction(NUC), dead correction replacement and temperature calculation at user's device
- The Android SDK, Windows DLL and Linux SO are available. It provides the output of thermal data and temperature data.

T.E. Hardware Platform

- The platform of T.E. hardware includes detector control, A/D conversion, USB communication and calibration data storage(in flash memory)
- There is no mechanical shutter. Shutterless algorithm is used to stabilize the output characteristics of the detector against the ambient temperature.

Product Mix / Images from the THERMAL EXPERT™



SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array Format	640 x 480
Pixel pitch	17 μ m
Wavelength band	8~14 μ m (Longwave infrared)
Sensitivity	≤ 50 mK@F/1, 300K
Frame rate	< 9 Hz or 30 Hz (Export Licence)
Scene range temperature	-10°C ~ 120°C
Operating temperature	-10°C ~ 50°C
Power Consumption	≤ 500 mW
Weight	< 60 g, without lens
Dimensions	50 mm x 32 mm x 30 mm, without Lens
Interface	Micro USB
Platform	Android, Windows
Type of lens	8.5mm, F/1.2 (Optional)
	19mm, F/1.0 (Default)
	25mm, F/1.2 (Optional)
	35mm, F/1.1 (Optional)
FOV	8.5 mm : 73.2° (H) x 54.5° (V) - 93.3. (diagonal)
	19 mm : 32.3° (H) x 24.4° (V) - 40.1. (diagonal)
	25 mm : 17.3° (H) x 13.1° (V) - 21.5. (diagonal)
	35 mm : 12.3° (H) x 9.3° (V) - 15.2. (diagonal)
Focus range	8.5 mm : 0.4 m to infinity
	19 mm : 2.4 m to infinity
	25 mm : 1.0 m to infinity
	35 mm : 5.0 m to infinity

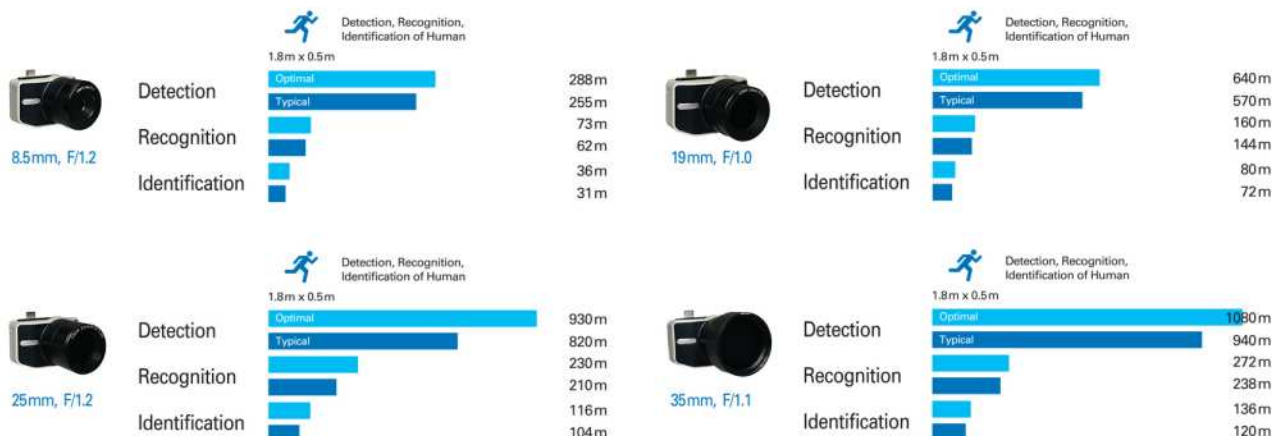
Software Platforms

Platform (OS)	Format
Windows	DLL
Android	SDK
Linux	SO

TE-V1 Dimensions



Range Performance



THERMAL EXPERT™

Mobile Infrared Camera

TE-Q1



6.8 mm Lens
Thermal Expert
SCENE RANGE
-10°C to 150°C



13 mm Lens
Thermal Expert PLUS
SCENE RANGE
-10°C to 120°C



6.8 mm Lens
Thermal Expert PRO
SCENE RANGE
-10°C to 250°C

Description

• High performance

- High resolution : 384 x 288 (17µm pitch)
- High sensitivity : ≤ 50 mK @ f/1.0, ≤ 80 mK @ f/1.3

THERMAL EXPERT™ for Android

- Color palettes (12 color maps)
- Storage images (IR, visible with snapshot and video)
- Digital zooming (384 x 288, 320 x 240, 240 x 160, 160 x 120)
- Image view with visible (50:50, Twin, Overlay, Floating)
- Temperature Measurement (Alarm, Min / Max, Point / Line / Rectangle / Circle profile)
- Report (Generate pdf report)
- Level and Span function (High Definition)



Level and Span

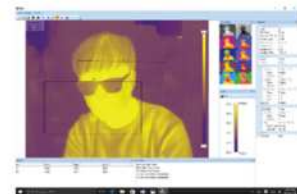


Features

- Temperature measurement for whole pixels
- Convenient image view functions with infrared and visible
- Easy graphical user interface (digital zooming, color Palette.)
- Interchangeable Lens

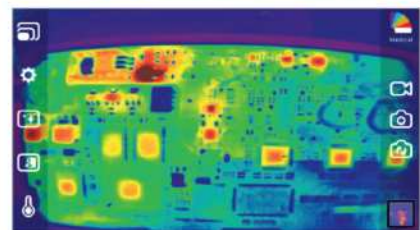
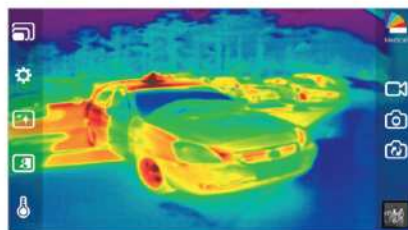
THERMAL EXPERT™ for Windows

- Realtime Analysis Tool
- Check the temperature anywhere in picture using mark of Dot, Line, Square
- Alarm with sound by user's setting temperature degree
- Save and Load infrared Image with mark
- Saving the movie with mark is being implemented
- AIE Program (Adaptive Image Enhancement)



Window PC program

Images from the THERMAL EXPERT™



SEE THE NEW WORLD THROUGH i3system, Inc.

Specifications

Array format	384 x 288
Pixel pitch	17 μm
Wavelength band	8 ~ 14 μm (Longwave Infrared)
Sensitivity	$\leq 50\text{mK}@F/1, 300\text{K}$ $\leq 80\text{mK}@F/1.3, 300\text{K}$
Frame rate	< 9Hz
Scene range temperature	-10°C ~ 150°C (PLUS : -10°C ~ 120°C, PRO : -10°C ~ 250°C)
Operating temperature	-10°C ~ 50°C
Power consumption	$\leq 500\text{mW}$
Weight	< 27g(with lens)
Dimensions(WxHxD)	47 mm x 25 mm x 16 mm (Without Lens)
Interface	Micro USB or USB-C
Platform	Android, Windows
Type of lens	Wide : 6.8 mm f/1.3 Narrow : 13 mm f/1.0
FOV[°]	Wide FOV(default) : 56.3°(H) x 41.8°(V) - 71.4°(diagonal) Narrow FOV(option) : 28.7°(H) x 21.7°(V) - 35.3°(diagonal)
Focus range	Wide FOV : 0.2m to infinity Narrow FOV : 0.4m to infinity

TE-Q1 Dimensions



Range Performance



THERMAL EXPERT™

Mobile Infrared Camera_Dev. Kit

TE-Q1 Dev. Kit

- Thermal Expert for third-party developer is composed of hardware and software.



6.8mm lens (default)



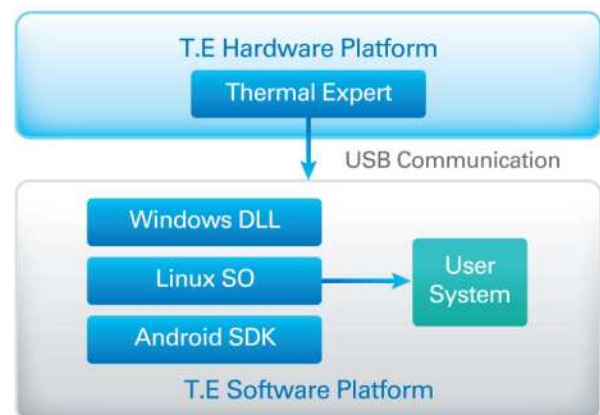
13mm lens (optional)

Description

- High resolution : 384 x 288 (17 μ m pitch)
- High sensitivity : $\leq 50\text{mK}@ f/1.0$, $\leq 80\text{mK}@ f/1.3$

Features

- Temperature measurement for whole pixels
- Interchangeable Lens
- Small sized hardware platform
- Various software platforms
- No shutter



T.E. Hardware Platform

- Hardware Platform has basic functions such as detector control, A/D conversion, USB communication and calibration data storage (in flash memory).
- There is no mechanical shutter. The algorithm is used to stabilize the output characteristics of the detector against the ambient temperature.

T.E. Software Platform

- Software Platform provides the calculation such as detector non-uniformity correction, dead pixel correction and temperature calculation in user system.
- The Android SDK, Windows DLL and Linux software platforms are available. Each provides the output of thermal data and temperature data.

Product Mix



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Specifications

Array format	384 x 288
Pixel pitch	17 μm
Wavelength Band	8~14 μm (Longwave Infrared)
Sensitivity	0.05 $^{\circ}\text{C}$ @ f/1.0
	0.08 $^{\circ}\text{C}$ @ f/1.3
Frame rate	< 9 Hz
Scene range temperature	-10 ~ 150 $^{\circ}\text{C}$ (f/1.3)
Operating temperature	-10 ~ 50 $^{\circ}\text{C}$
Power consumption	$\leq$ 500 mW
Weight	< 27 g (with Wide FOV Lens)
Dimensions(W x H x D)	47 mm x 25 mm x 16 mm (Without Lens)
Interface	Micro USB or USB-C
Type of lens	Wide: 6.8mm f/1.3
	Narrow: 13mm f/1.0
FOV[$^{\circ}$]	Wide FOV (default) : 56.3 $^{\circ}$ (H) x 41.8 $^{\circ}$ (V) - 71.4 $^{\circ}$ (diagonal)
	Narrow FOV (option) : 28.7 $^{\circ}$ (H) x 21.7 $^{\circ}$ (V) - 35.3 $^{\circ}$ (diagonal)
Focus range	Wide FOV : 0.2m to infinity
	Narrow FOV : 0.4m to infinity

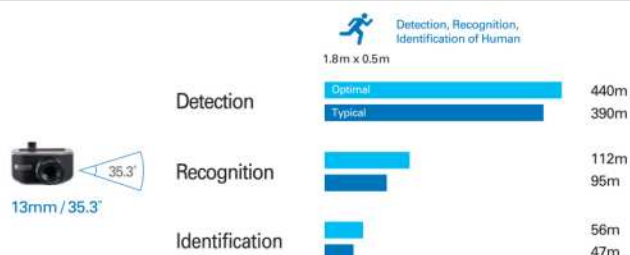
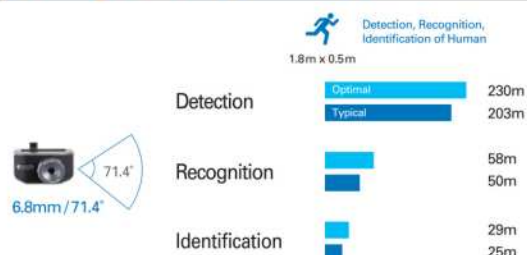
Software platforms

Platform (OS)	Format
Windows	DLL
Android	SDK
Linux	SO

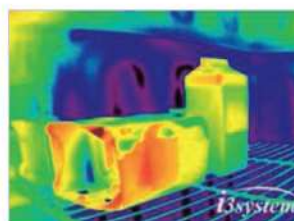
TE-Q1 Dimensions

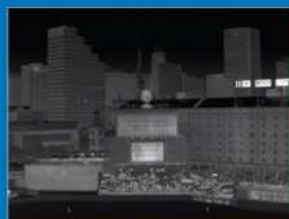


Range Performance



Thermal Images





Intelligent Image & Information System

i3system

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